

Form 1449 (Revised)

Information Disclosure Statement By Applicant

(Use Several Sheets if Necessary)

Atty Docket No. NSC1P131X3/P04314P03 Application No.: 10/707,208

Applicant: Patwardhan et al.

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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
WZ	A	6,288,444 B1	09/11/01	Abe et al.			06/04/99
	B						
	C						
	D						
	E						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
	F						Yes	No
	G							
	H							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
WZ	I	Kulicke & Soffa, "Flip Chip Products, Polymer Collar™ Wafer Level Package; Achieve Maximum Reliability for Wafer Level Packages!", December 7, 2001, pp. 1-2 www.kns.com
WZ	J	Kulicke & Soffa, "Flip Chip Division, Polymer Collar Wafer Level Package; See the Polymer Collar WLP difference!", December 7, 2001, pp. 1-2 www.kns.com
WZ	K	"Fundamentals of Microsystem Packaging", Rao R. Tummala, Chapters 2, 10, and 17, (May 8, 2001) McGraw-Hill Professional Publishing
WZ	L	"Chip Scale Package: Design, Materials, Process, Reliability, and Applications", John H. Lau and S.W. Ricky Lee, Chapter 1, Pages 1-41, (February 28, 1999) McGraw-Hill Professional Publishing
Examiner	Date Considered	
WZ	9/13/05	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.